



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Blalock et al.

**Serial No.:** 10/229,868

**Filed:** August 27, 2002

**For:** DEADHESION METHOD AND  
MECHANISM FOR WAFER PROCESSING

**Confirmation No.:** 2027

**Examiner:** Unknown

**Group Art Unit:** 2812

**Attorney Docket No.:** 2269-3549.2US

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

November 27, 2002  
Date

Signature

Deidra J. Pfeil  
Name (Type/Print)

**LETTER TO THE CHIEF DRAFTSMAN**

Box Non-Fee Amendment  
Commissioner for Patents  
Washington, D.C. 20231

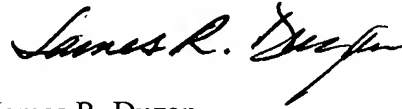
Sir:

Applicants submit herewith revised FIGS. 2 and 13 which correct errors in the drawings. Specifically, FIG. 2 has been revised to change the reference numeral "21" to --18-- to eliminate redundancy with previously used reference numerals; and FIG. 13 has been revised to extend the lead line for reference numeral "629." Attached is a copy of the drawings with the proposed changes marked in red.

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No new matter has been added. Approval of the proposed revisions is respectfully requested.

Respectfully submitted,



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JRD/csw

Enclosures: Drawings with changes marked in red

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